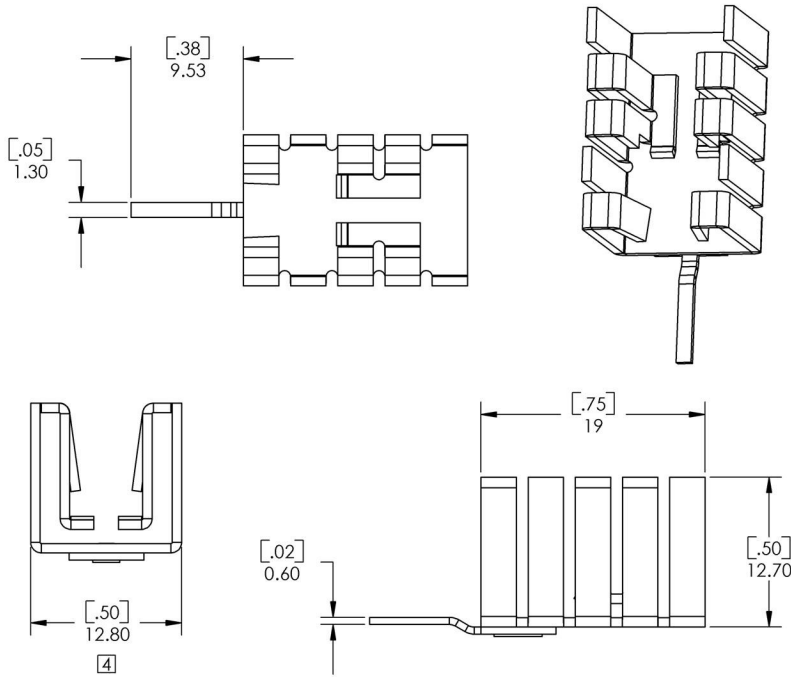
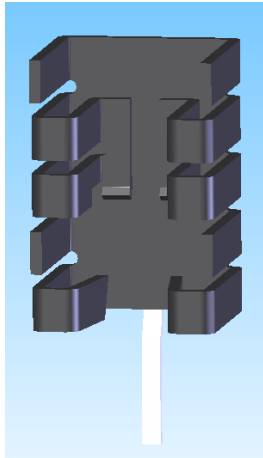


Board Level Heat Sinks



ThermaFlo

P/N: 831502B03900



PRODUCT SPECIFICATIONS

- Devices: TO-220 & TO-262
- Size: 19.0 x 12.8 x 12.7 mm
- Material: Aluminum, 1.2 mm Thick
- Type: Stamped
- IC Mounting: Integrated Spring
- PCB Mounting: Solderable Tab
- Finish: Black Anodized
- Package: Bulk

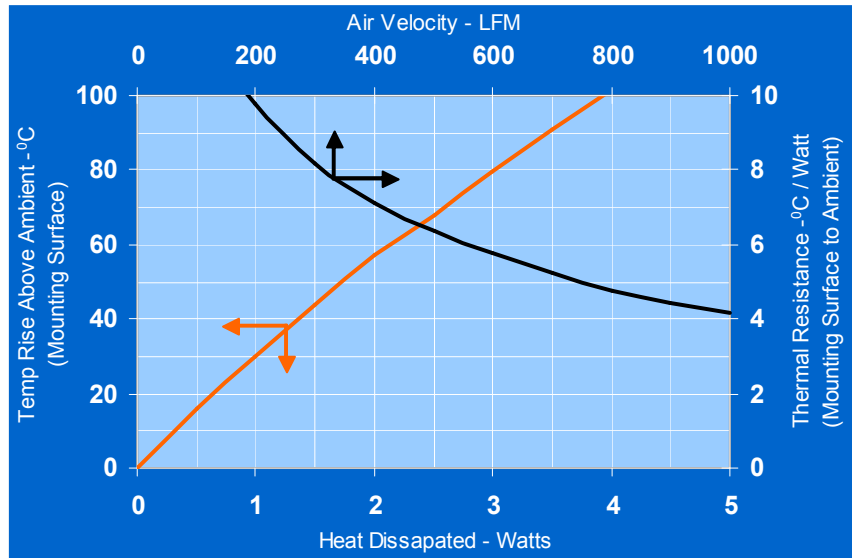
FEATURES & BENEFITS

- No Hardware Device Attachment
- Constant Spring Force Tension
- Vertical Mounting via Solderable Tab
- RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Tabs, Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220, TO-262

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